

What Is Claimed Is:

1. A sensor system, comprised of
 - a thin-film sensor (1) having at least one contacting area (1.1a, 1.1b) on its surface (Z) and
 - a printed circuit board (2) having at least one contact pad (2.1a, 2.1b) on its surface (A),

the thin-film sensor (1) being placed in such a way relative to the surface (A) of the printed circuit board (2) that the surface (Z) of the thin-film sensor (1) faces away from the surface (A) of the printed circuit board (2), and

a conductive adhesive (3) for transmitting sensor currents from the thin-film sensor (1) to the printed circuit board (2) adheres both

 - to the contacting area (1.1a, 1.1b) of the thin-film sensor (1) and
 - to the contact pad (2.1a, 2.1b) on the surface (A) of the printed circuit board (2).
2. The sensor system as recited in Claim 1, wherein the thin-film sensor (1) is a humidity sensor.
3. The sensor system as recited in Claim 2, wherein the functioning method of the thin-film sensor is based on a capacitive measuring principle.
4. The sensor system as recited in one of Claims 1 through 3, wherein the thin-film sensor (2) has two contacting areas (1.1a, 1.1b), each joined by a conductive adhesive (3) to one contact pad (2.1a, 2.1b) of the printed circuit board (2).

5. The sensor system as recited in one of Claims 1 through 4, wherein a mounting adhesive (4) is disposed at least in one partial area between the thin-film sensor (1) and the printed circuit board (2).
6. The sensor system as recited in Claim 5, wherein the mounting adhesive (4) exhibits a thermal conductivity greater than $0.3 \text{ W/(m}\cdot\text{K)}$.
7. A method for manufacturing a sensor system, comprising the following steps:
 - (S2) placing a thin-film sensor (1) in such a way relative to a surface (A) of a printed circuit board (2) that a surface (Z) of the thin-film sensor (1), on which a contacting area (1.1a, 1.1b) is situated, is facing away from the surface (A) of the printed circuit board (2);
 - (S3) bonding the thin-film sensor (1) to the printed circuit board (2) in the manner that the contacting area (1.1a, 1.1b) of the thin-film sensor (1) is electrically connected by a conductive adhesive (3) to a contact pad (2.1a, 2.1b) on the surface (A) of the printed circuit board (2).
8. The method as recited in Claim 7, wherein a mounting adhesive (4) is applied (S1) prior to placing (S2) a thin-film sensor (1) on a surface (A) of a printed circuit board (2).